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# SIXTH SEMESTER B.TECH. (ENGINEERING) DEGREE EXAMINATION, APRIL 2017

Electronics and Communication Engineering EC 14 603-VLSI DESIGN

**Time : Three Hours** 

Maximum: 100 Marks

# Answer any eight questions. Each question carries 5 marks.

- 1. (a) Give the principle of constant field scaling and its effect on device characteristics.
  - (b) Discuss the operation of CMOS ring oscillator. Estimate its frequency.
  - (c) Explain the problem of charge sharing and how it is overcome.
  - (d) Discuss the operation of differential sense amplifier.
  - (e) Explain the operation of ROM using pseudo NMOS logic.
  - (f) Explain the logic behind carry look ahead adder.
  - (g) Discuss the process of molecular beam epitaxy.
  - (h) Outline the various types of photoresists.
  - (i) Write short notes on multi-level metallization.
  - (j) Explain the layout process using cell hierarchy.

# $(8 \times 5 = 40 \text{ marks})$

- 2. (a) (i) Obtain the d.c. transfer characteristics of pseudo NMOS inverter. (8 marks)
  - (ii) Outline the reason for power dissipation and various sources that lead to power dissipation.

(7 marks)

(7 marks)

(10 marks)

(5 marks)

Or

- (b) (i) Discuss the various factors that account to robustness of CMOS inverter. (8 marks)
  - (ii) Explain channel length modulation and body effect.
- 3. (a) (i) Draw and explain the architecture of Carry Select Adder. Outline how it does increase the speed of operation.
  - (ii) Explain the structure of 6T SRAM cell.

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(5 marks)

(b) (i) Explain the architecture of  $4 \times 4$  array multiplier with neat diagram. (10 marks)

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- (ii) Draw and explain the structure of 4: 1 Multiplexer using transmission gate. (5 marks)
- 4. (a) (i) Explain in detail the Deal Grove model of oxidation process.(10 marks)(ii) Write short notes about ion implantation.(5 marks)

#### Or

- (b) Define etching. Explain the principles of wet and ion etching. Differentiate the key points between them.
- 5. (a) (i) Explain the steps involved in twin tub process of CMOS fabrication.(10 marks)(ii) Discuss the lambda based design rules.(5 marks)

#### Or

(b) (i) Draw the stick diagram of NAND gate.(5 marks)(ii) Explain the principle of silicon on insulator isolation.(10 marks)[4 × 15 = 60 marks]

Law Samer